



EXPERT 10.6 RS

5,300 W Rework station

Semi-automated rework station with Gantry system for small to very large and massive components. The proven hybrid underheater allows gentle heating of boards with dimensions up to 500x500 mm². For safe handling of all components, the precise positioning

system can navigate to any point on the PCB. Pre-positioning is performed via the smooth-running XY gantry, while fine positioning and placement is fully automatic using reliable Martin precision/-technology.

Top Features

Camera-supported rework



Flexibility

Good accessibility of all components on the board via the gantry system & compact footprint at the same time



Under-heating system

Large PCBs 500 x 500 mm²



Performance

High cycle time due to easy prepositioning of the arm via gantry system



Multifunctionality

One device for all processes, including desoldering, pad cleaning, automatic positioning and soldering



Process control

Automatic profiler for under- and top-heating systems



Software

Simple, intuitive, tablet-compatible

Standard equipment

- Tool set for placing, residual solder removal and soldering with magazine
- Set of placement nozzles XL-type (BGA/CSP) 5 mm, 8 mm, 15 mm with O-Ring
- Set of solder nozzles (BGA) 15 mm, 27 mm, 35 mm, 40 mm
- Two camera lenses (BGA, CSP)
- Two thermocouple sensors (type K)
- Four PCB magnet holder 40.5 mm (standard)
- Two PCB clips to install at hand rest
- Manual
- Intuitive software EASYSOLDER 07 with touch integration

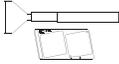
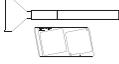
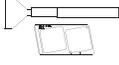
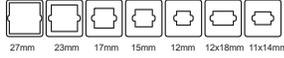
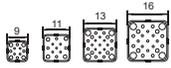
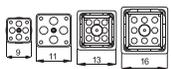
Technical details

Power consumption:	5500 VA	
Power solder pen:	400 W, 35 l/min	
Power under-heating system:	1200 - 5000 W	8 x IR-lamps
Size under-heating system:	450 x 420 mm ²	
Max. PCB size:	500 x 500 mm ²	
Resolution motion system:	0.001 mm	
Placement accuracy:	± 0.015 mm	(Flip Chip)*
	± 0.030 mm	(CSP)
	± 0.040 mm	(BGA)
	± 0.070 mm	(Maxi BGA)*
	± 0.115 mm	(Maxi BGA XL)*

High resolution CMOS-camera:	5 Mio. Pixel USB2	
Camera field of view (FOV):	16 x 22 mm ²	(Flip Chip)*
	32 x 42 mm ²	(CSP)
	42 x 57 mm ²	(BGA)
	71 x 96 mm ²	(Maxi BGA)*
	115 x 160 mm ²	(Maxi BGA XL)*
Mains:	1Phase, 230VAC, Fuse 25A	
	Connector Type CEE 32A (3 phase)	
Pressurized air:	5-8 bar, 100 l/min	clean, dry air
Dimensions:	1030 x 630 mm ²	

*Optional extras

EXPERT 10.6 RS: Optional extras

	Article nr.	Name
	SF66.0501	Tool Shuttle 40 for AVP 4.1XL
	SF64.0525	Dip Tool 0.08mm with squeegee for tool shuttle 32 / 40
	SF64.0526	Dip Tool 0.15mm with squeegee for tool shuttle 32 / 40
	SF64.0527	Dip Tool 0.22mm with squeegee for tool shuttle 32 / 40
	SF66.0526	Dip Tool 0.15mm with squeegee for tool shuttle 40 only
	AT10.0100	Chip Frame Set Dip Tool 7 / 32*32mm 7 pcs (11*14,12*18,12,15,17,23,27)
	AT20.0100	Chip Frame Set Dip Tool 7 / 40*40mm 7 pcs (15,17,23,27,31,35,37.5)
	SF64.0520	Print Tool with squeegee for tool shuttle 32 / 40
	DB00.0025	Nitrogen input for DBL 04/05/06 (2.p.r) reduces consumption of N2 for vacuum
	SF66.0110	Lens Maxi BGA for AVP4/4XL, f=16mm, 65*85mm
	LW40.1096	Soldering nozzle set CSP/QFN 4 for all CSP types, 4 pieces (9, 11, 13, 16)
	LW40.1104	Soldering nozzle set CSP with vacuum 4 for all CSP types, 4 pieces (9, 11, 13, 16)
	LW40.1099	Solder Nozzle Set BGA 7 7 pieces (15, 23, 27, 31, 35, 37.5, 40)
	SF36.1002	PCB flex support h=40.5 mm for HIF 09, "12 pin"
	SF71.0005	Side Camera (lens 16mm) for ES 05/07, camera, stand, cable
	SF71.0004	Side Camera (lens 35mm) for ES 05/07, camera, stand, cable
	SF71.0007	Lens for side camera f=16mm
	SF71.0011	Lens μSMD for side camera f=35mm

Additional accessories and consumables are available on www.martin-smt.de/en/shop/